フラックス残渣レスソルダペースト
Flux residual-less solder paste

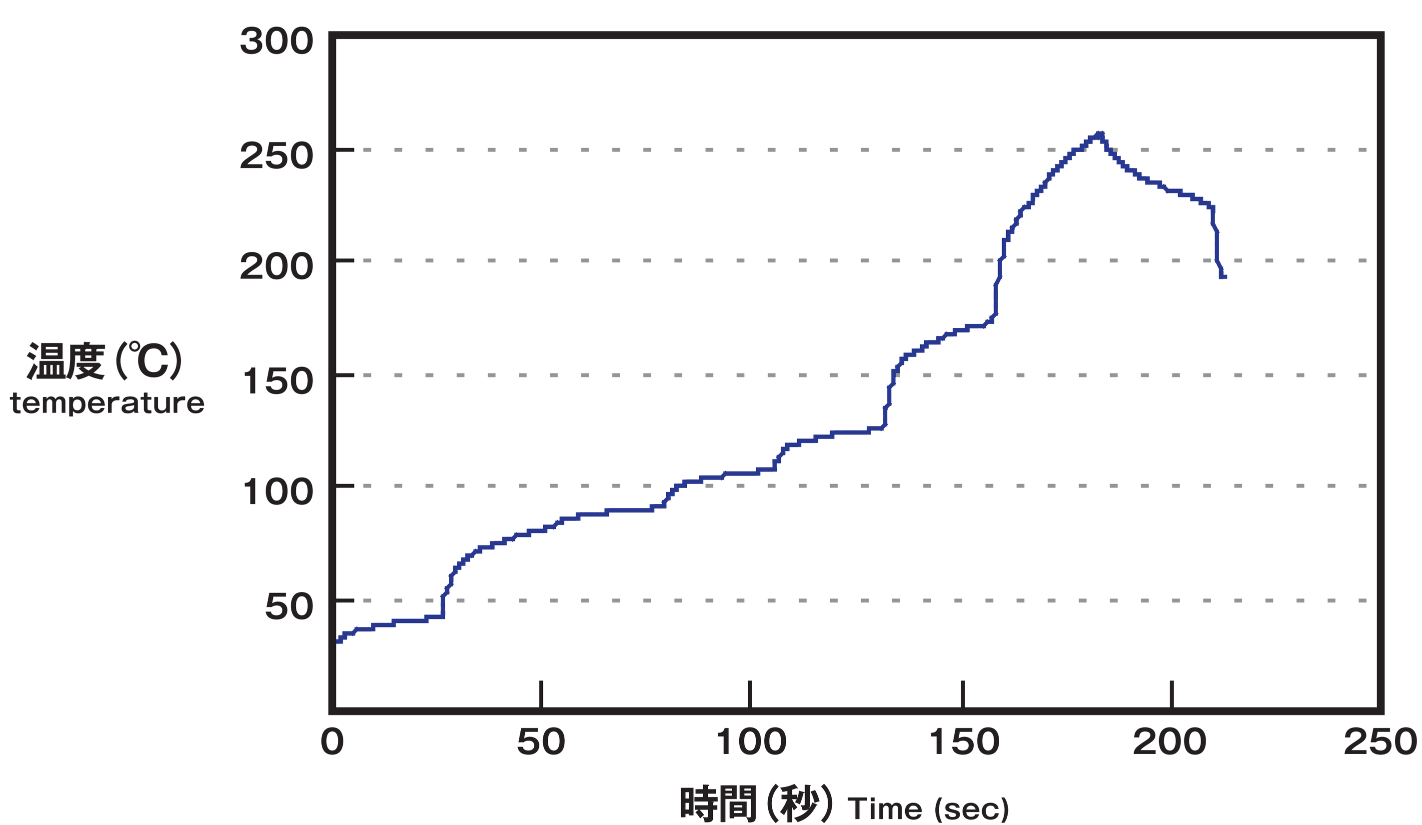
NP303-FLV-T4

フラックス残渣が残らず洗浄不要!
Since flux residue does not remain, cleaning is unnecessary!

Ni などのヌレにくい母材に対してもヌレ性良好!
Wettability to parts that are hard to get wet like Ni is also good!

N2+真空リフロー対応でボイド発生を抑制!
Void suppression by N2 + vacuum reflow furnace!

リフロー後の試験片の状態
Sample state after reflow

	試験片の状態 Sample state	
Ni へのヌレ性 Wettability to nickel		ヌレ性良好! Good wettability !
SEM 観察結果 SEM observation result		フラックス残渣無し! There is no residue of flux!

推奨リフロープロファイル
Recommended reflow profile

温度 (℃) temperature
300
250
200
150
100
50
0 50 100 150 200 250
時間 (秒) Time (sec)

	試験条件 Test condition	推奨条件 Recommended conditions
昇温速度 Temperature increase rate	1.0sec.	2sec. 以下
プリヒート (100℃-170℃) Preheat	60.8sec.	40-70sec.
昇温速度 (170℃-220℃) Temperature increase rate	4.6℃/sec.	4℃/sec. 以上
>220℃	46sec.	30-90sec.
ピーク温度 Peak temperature	260.6℃	250-270℃
酸素濃度 Oxygen concentration	500ppm	500ppm 以下
真空到達度 Vacuum reach	3.9kPa	10kPa 以下

低融点微細粉エポキシ樹脂系ソルダペースト
Epoxy resin-based fine solder paste with low melting temperature

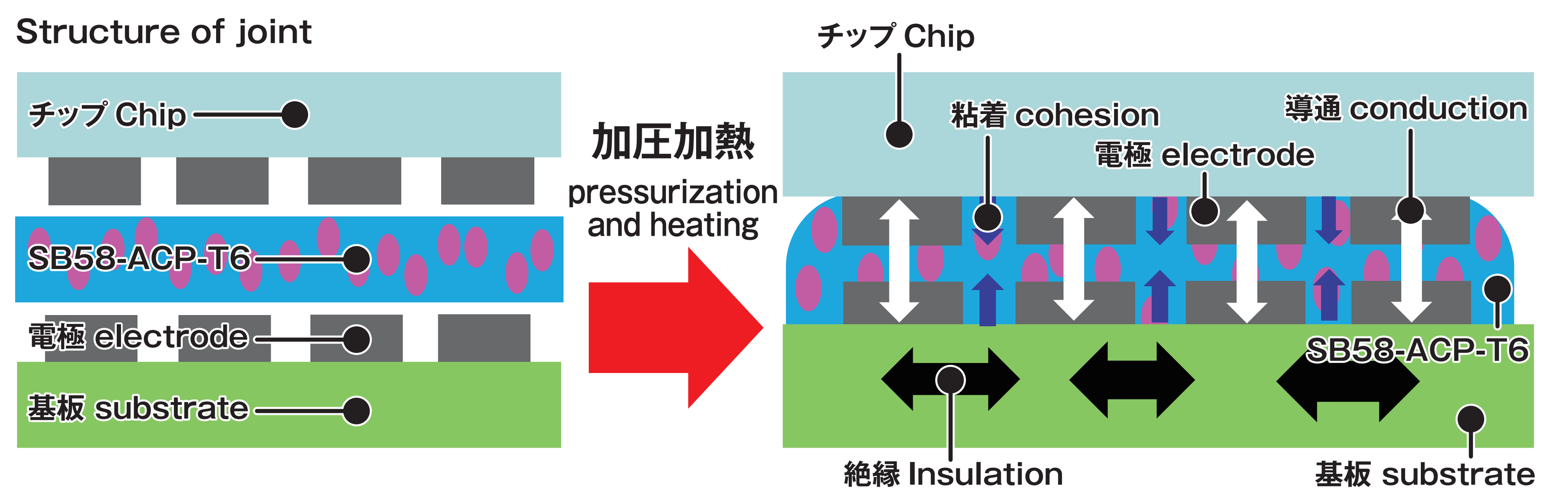
SB58-ACP-T6

導電性接着剤に代わる低融点エポキシ樹脂系はんだ
Epoxy resin-based solder paste with low melting temperature as an alternative to conductive adhesives

加圧加熱方式対応
Applicable for soldering with pressing by heating tool

電極間にはんだ粉末が残留分散
Disperse solder powder between pads

接合原理
Structure of joint



ACP(一般品)
general products

SB58-ACP-T6

ACP と同等の分散性により絶縁性実現
Achieves insulating properties with dispersibility equivalent to ACP

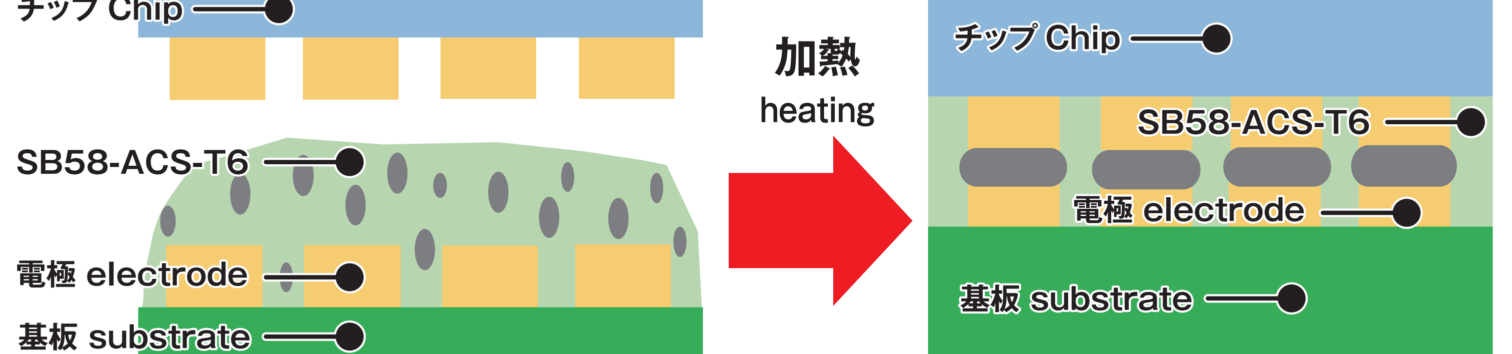
SB58-ACS-T6

導電性接着剤に代わる低融点エポキシ樹脂系はんだ
Epoxy resin-based solder paste with low melting temperature as an alternative to conductive adhesives

リフロー・オーブン方式対応
Applicable for soldering by reflow oven

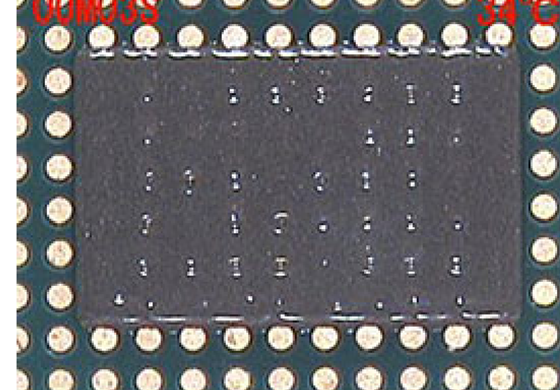
電極間にはんだ粉末が残留せず、凝集
Solder self-assembling on pads without remaining solder between pads

接合原理 Principle of joint

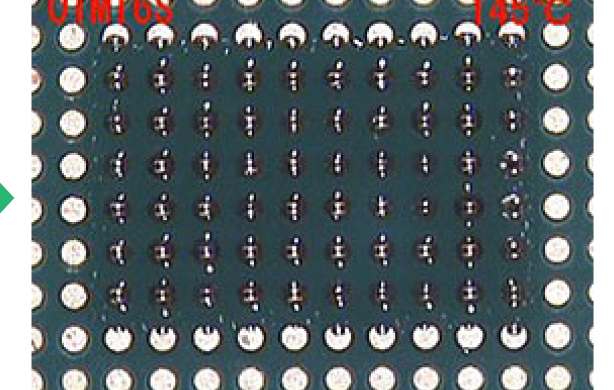


加熱すると電極部分にはんだ粒子が凝集
Solder self-assembling on the electrode pads at melting

全面印刷 Enlarged printing



溶融 melting



全面印刷から電極上のみに凝集
After printing on the entire surface, cohesion is achieved using only the pad.

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